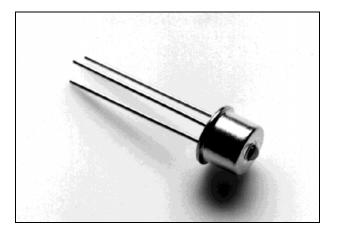
#### **Data Sheet**

September 2004



#### **Features**

- 820 nm Surface-Emitting LED
- · 250 MHz Bandwidth
- Designed for 62.5/125 µm fiber
- High linearity

## **Applications**

- FM Video
- · Computer graphics
- LANs

### **Ordering Information**

MF388 TO-46 Package MF388 ST ST Housing

#### -40°C to +85°C

Note:Rated Fiber coupled power apply only on the TO-46 package, for housing options fiber coupled power is typically 10% less.

## **Description**

This device is designed for Ethernet 100 Mbps and Intra-Office Telecom applications and offers an excellent price/performance ratio for cost effective solutions. Its double-lens optical system results in optimum coupling of power into the fiber.

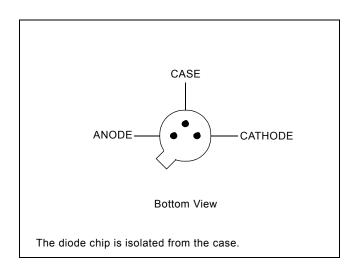


Figure 1 - Pin Diagram

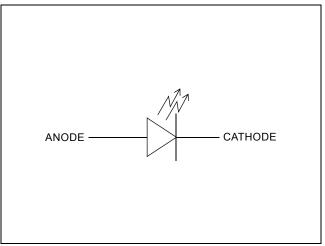


Figure 2 - Functional Schematic

# Optical and Electrical Characteristics - Case Temperature 25°C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Condition	
Fiber-Coupled Power (Figures 3, 4, and 5) (Table 1)	P <sub>fiber</sub>	40	50		μW	I <sub>F</sub> =50 mA (Note 1)	Fiber: 62.5/125 μm
Rise and Fall Time (10-90%)	t <sub>r</sub> ,t <sub>f</sub>			2	ns	I <sub>F</sub> =50 mA (no bias)	Graded Index
Bandwidth (3 dB <sub>el</sub> )	f <sub>c</sub>	200	250		MHz	I <sub>F</sub> =50 mA	NA=0.275
Peak Center Wavelength	$\lambda_{p}$	800	820	840	nm	I <sub>F</sub> =50 mA	
Spectral Width (FWHM)	Δλ			60	nm	I <sub>F</sub> =50 mA	
Forward Voltage (Figure 7)	V <sub>F</sub>			1.85	V	I <sub>F</sub> =50 mA	
Reverse Current	I <sub>R</sub>			20	μΑ	V <sub>R</sub> =1 V	
Capacitance	С		20		pF	V <sub>R</sub> -0 V, f=1 MH	Hz

Note 1: Measured at the exit of 100 meters of fiber.

# **Absolute Maximum Ratings**

Parameter	Symbol	Limit	
Storage Temperature	T <sub>stg</sub>	-55 to +125°C	
Operating Temperature (derating: Figure 6)	$T_{op}$	-40 to +85°C	
Electrical Power Dissipation (derating: Figure 6)	P <sub>tot</sub>	250 mW	
Continuous Forward Current (f<10 kHz)	I <sub>F</sub>	110 mA	
Peak Forward Current (duty cycle<50%,f>1 MHz	I <sub>FRM</sub>	180 mA	
Reverse Voltage	$V_{R}$	1.5 V	
Soldering Temperature (2 mm from the case for 10 sec.)	$T_{sld}$	260°C	

## **Thermal Characteristics**

Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal Resistance - Infinite Heat Sink	R <sub>thjc</sub>			100	°C/W
Thermal Resistance - No Heat Sink	R <sub>thja</sub>			400	°C/W
Temperature Coefficient - Optical Power	$\mathrm{d}P/\mathrm{d}T_{\mathrm{j}}$		-0.6		%/°C
Temperature Coefficient - Wavelength	$\mathrm{d}\lambda/\mathrm{d}T_\mathrm{j}$		0.3		nm/°C

# **Typical Fiber-Coupled Power**

Core Diameter/Cladding Diameter Numerical Aperture						
50/125 μm 0.20	62.5/125 μm 0.275	100/140 μm 0.29	200/230 μm 0.37			
20 μW	50 μW	100 μW	140 μW			

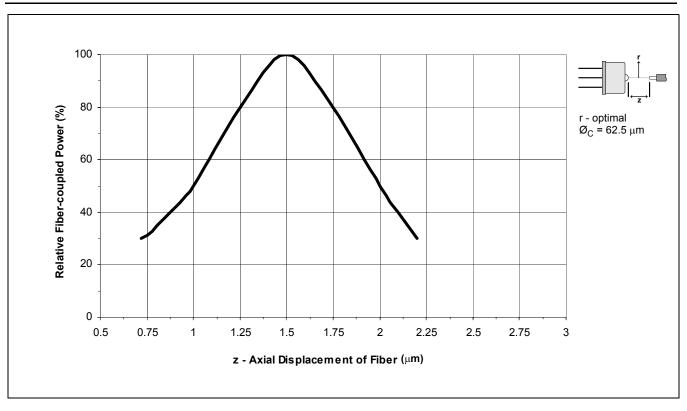


Figure 3 - Relative Fiber-coupled Power vs. z - Axial Displacement of Fiber

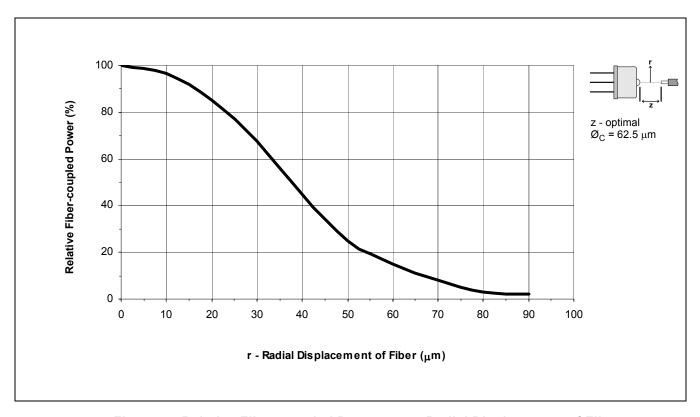


Figure 4 - Relative Fiber-coupled Power vs. r - Radial Displacement of Fiber

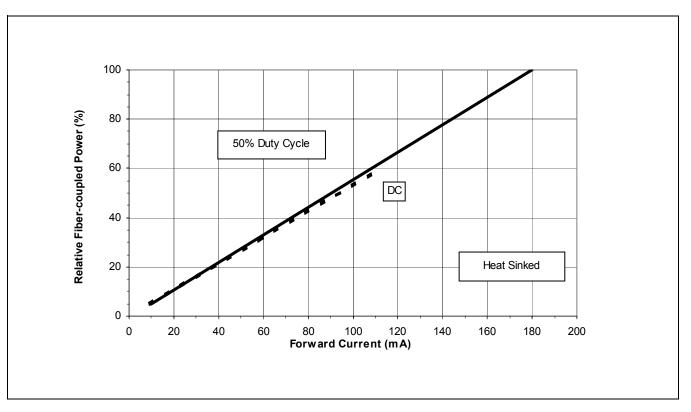


Figure 5 - Relative Fiber-coupled Power vs. Forward Current

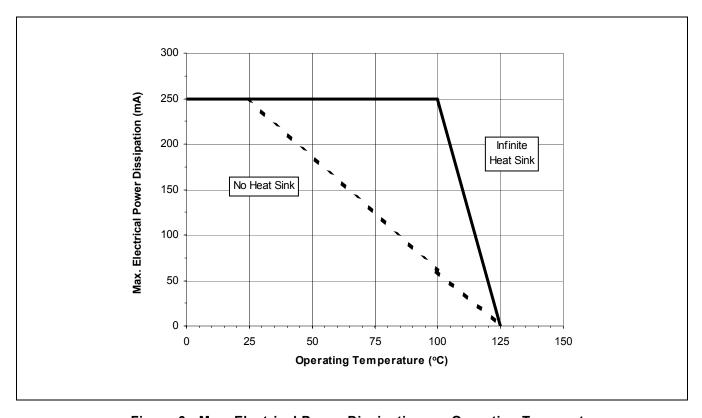


Figure 6 - Max. Electrical Power Dissipation vs. Operating Temperature

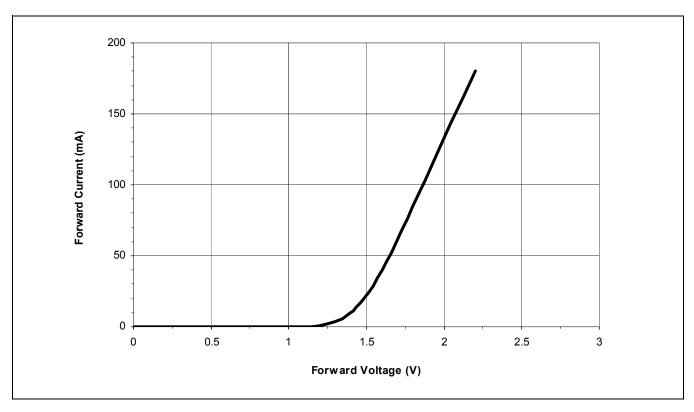
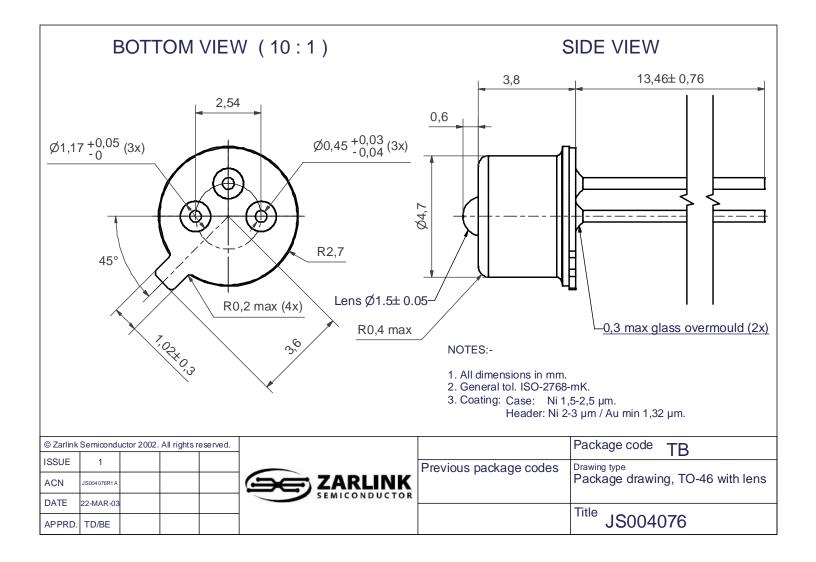


Figure 7 - Forward Current vs. Forward Voltage





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